

AIM SOLDER PASTE HANDLING GUIDELINES

TRANSPORTATION

- AIM solder paste is shipped to maintain product temperature between 0°C - 30°C by using refrigerated transport or ice packs within the packaging
- Cold packs may have melted by arrival but is not an indication of paste mishandling. Paste should be transferred immediately to controlled storage area

PREPARATION FOR USE

- Remove AIM paste product from controlled storage and label with date and time of removal from storage for your records
- **IMPORTANT** Allow proper amount of time to pass for paste to properly reach ambient temperature 68°-77°F (20°-25°C) before use
DO NOT FORCE WARM PASTE OR USE IT COLD
- Solder paste in jars should be stirred with a plastic tool lightly and thoroughly for one minute

STENCIL APPLICATION

- Carefully add paste to the printer. Paste should cover the length of the stencil and should be about 3/8 of an inch thick

STORAGE

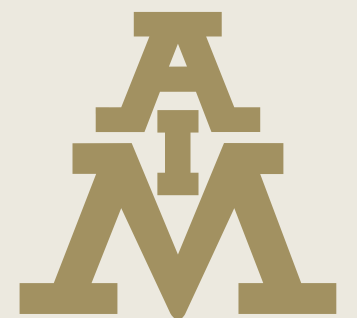
- Refrigeration is recommended but may not be required. Refer to product specific TDS and Certificate of Analysis for storage and shelf life recommendations
- **AFTER USE** Remove paste from the printer and place in a clearly labeled container for used paste
DO NOT COMBINE NEW AND USED solder paste in the same container
- Solder paste should not be re-refrigerated after opening, any opened material should be resealed and stored at room temperature

ENVIRONMENTAL CONDITIONS

- For optimal results, the production area should be maintained at a temperature of 22°- 26°C (72°-80°F) at 45% ±5% relative humidity
- Paste performance can be affected by under-stencil wipe solvents
AIM DJAW-10 is compatible with all AIM Pastes/IPA not recommended

To download or for more information visit

www.aimsolder.com



Solder plus Support